



GAU 2841

Patent  
Docket No: 52779USA1B.008

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Yu Chen, Joel A. Gerber, Brian E. Schrieber and  
Joshua W. Smith

Serial No.: 09/531,285

Filed: March 20, 2000

For: CIRCUIT ELEMENTS USING A Z-AXIS  
INTERCONNECT

Group Art Unit: 2841

Examiner: J. Vigushin

3/24/01  
AG/Am d+C  
R. Tyson

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MAR 23 2001  
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AMENDMENT UNDER 37 C.F.R. § 1.111

Commissioner for Patents  
Washington, DC 20231

Dear Sir:

3/24/01  
This amendment replies to the Official Action mailed January 11, 2001 in which claims 37-43 were rejected. With this amendment, claims 37 and 38 are amended, and claim 43 is canceled from the application.

Please amend the application as described in further detail below.

In the Specification:

Please amend the specification as follows:

On Page 1, the title should be changed to correspond to the title on the Transmittal Letter filed with the application as follows:

CIRCUIT ELEMENTS USING A Z-AXIS INTERCONNECT

On Page 1, insert as the first paragraph the following paragraph:

C1  
This is a divisional of Application No. 08/986,882, now allowed as U.S. Patent No. 6,063,647.

Amend the first complete paragraph on page 3 as follows:

C2  
U.S. Patent No. 5,502,889 (Casson et al.) discloses a method for fabricating a multilayer circuit board, that uses an anisotropically conducting adhesive to connect multiple layers of double sided circuitry. However, the resultant circuit has drawbacks, in that the use of a random dispersion of particles can not provide the high density of hole (or via)

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Washington, DC 20231 on:

3-15-01  
Date

Signature Tom Sanders